L Number	Hits	Search Text	DB	Time stamp
Number	0	pacholik-robert.in.	USPAT;	2003/07/30
-		F	US-PGPUB;	13:40
			EPO; JPO;	
			DERWENT	
2	0	lidmer-gunnar.in.	USPAT;	2003/07/30
			US-PGPUB;	13:41
			EPO; JPO;	
	120072		DERWENT	2003/07/30
3	138973	printed adj circuit adj board	USPAT;	13:41
			US-PGPUB; EPO; JPO;	13:41
			DERWENT	
4	48432	electroplating	USPAT;	2003/07/30
•		olootiopiusing	US-PGPUB;	13:42
			EPO; JPO;	
			DERWENT	
5	3554	(printed adj circuit adj board) and	USPAT;	2003/07/30
		electroplating	US-PGPUB;	13:42
1			EPO; JPO;	
1 _			DERWENT	
6	352604	etching	USPAT;	2003/07/30
			US-PGPUB;	13:42
			EPO; JPO; DERWENT	
7	2158	etching and ((printed adj circuit adj	USPAT;	2003/07/30
'	2130	board) and electroplating)	US-PGPUB;	13:43
		board, and creecropracing,	EPO; JPO;	13.13
			DERWENT	
8	2822	electrolysis with copper	USPAT;	2003/07/30
			US-PGPUB;	13:43
			EPO; JPO;	
			DERWENT	
9	31	(etching and ((printed adj circuit adj	USPAT;	2003/07/30
		board) and electroplating)) and	US-PGPUB;	13:51
		(electrolysis with copper)	EPO; JPO;	
10	63729	gonnon glm	DERWENT USPAT;	2003/07/30
	03729	copper.clm.	US-PGPUB;	13:51
			EPO; JPO;	13.31
			DERWENT	
11	882	(etching and ((printed adj circuit adj	USPAT;	2003/07/30
		board) and electroplating)) and	US-PGPUB;	13:52
		copper.clm.	EPO; JPO;	
			DERWENT	
12	1097480	organic	USPAT;	2003/07/30
			US-PGPUB;	13:53
			EPO; JPO;	
13	439	   ((etching and ((printed adj circuit adj	DERWENT USPAT;	2003/07/30
10	433	((etching and ((printed ad) circuit ad)	US-PGPUB;	13:53
		copper.clm.) and organic	EPO; JPO;	-5.55
			DERWENT	
14	245157	recycl\$	USPAT;	2003/07/30
			US-PGPUB;	13:54
1	!		EPO; JPO;	
		[	DERWENT	
15	18	(((etching and ((printed adj circuit adj	USPAT;	2003/07/30
		board) and electroplating)) and	US-PGPUB;	13:58
		copper.clm.) and organic) and recycl\$	EPO; JPO;	
16	35240	205/\$.ccls.	DERWENT	2003/07/20
10	33240	200/ Y. CCI3.	USPAT; US-PGPUB;	2003/07/30 13:58
			EPO; JPO;	13.30
			DERWENT	
18	13	recycl\$ and (205/\$.ccls. and (printed adj	USPAT;	2003/07/30
	_ ,	circuit adj board) and electroplating and	US-PGPUB;	13:59
		etching)	EPO; JPO;	
			DERWENT	

17	286	205/\$.ccls. and (printed adj circuit adj	USPAT;	2003/07/30
i		board) and electroplating and etching	US-PGPUB;	14:24
			EPO; JPO;	
			DERWENT	
19	485148	waste	USPAT;	2003/07/30
			US-PGPUB;	14:25
			EPO; JPO;	
			DERWENT	1
20	233	(etching and ((printed adj circuit adj	USPAT;	2003/07/30
		board) and electroplating)) and waste	US-PGPUB;	14:25
			EPO; JPO;	
	-		DERWENT	
21	36	recycl\$ and ((etching and ((printed adj	USPAT;	2003/07/30
		circuit adj board) and electroplating))	US-PGPUB;	14:29
		and waste)	EPO; JPO;	
			DERWENT	
22	36	recycl\$ and ((etching and ((printed adj	USPAT;	2003/07/30
		circuit adj board) and electroplating))	US-PGPUB;	14:30
		and waste)	EPO; JPO;	
			DERWENT	
23	13	recycl\$ and (205/\$.ccls. and (printed adj	USPAT;	2003/07/30
		circuit adj board) and electroplating and	US-PGPUB;	14:32
		etching)	EPO; JPO;	
			DERWENT	
24	89	(205/297).CCLS.	USPAT;	2003/07/30
			US-PGPUB;	14:36
			EPO; JPO;	
			DERWENT	